

## Electrostatic Discharged Protection Devices (ESD) Data Sheet

### Description

Brightking's LBT23C24L02 component is designed to protect sensitive electronics from damage or latch-up due to ESD and other voltage induced transient events. It is designed for use in applications where board space is at a premium. The device will protect up to two lines. It is bidirectional devices and may be used on lines where the signal polarities are above ground. TVS diodes are solid state device designed specifically for transient suppression. It feature large cross-sectional area junctions for conduction high transient currents. It offer desirable characteristics for board level protection including fast response time, low and clamping voltage, and no device degradation. The device may be used to meet the immunity requirements of IEC61000-4-2, level 4. The size SOT-23 package makes them ideal for use in portable electronics such as RS-422 I/Os, RS-232 I/Os, notebook computers, and servers.



Contact : ±8kV  
Air : ±15kV



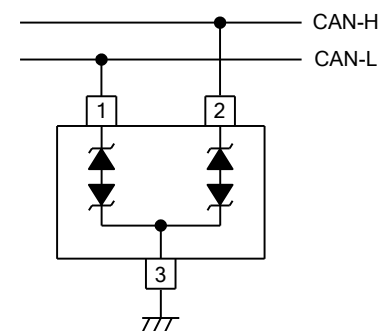
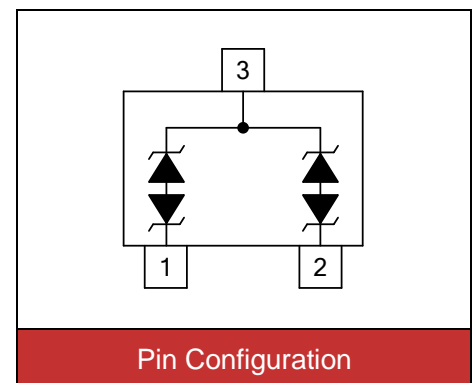
### Features

- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- SOT-23 surface mount package
- Protects bidirectional two I/O lines
- Working voltage: 24V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: B L24

### Applications

- CAN bus protection
- Automotive applications

### Maximum Ratings



Rating	Symbol	Value	Unit
ESD voltage (Contact discharge)	$V_{ESD}$	$\pm 8$	kV
ESD voltage (Air discharge)		$\pm 15$	
Storage & operating temperature range	$T_{STG}, T_J$	-55~+150	°C

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ )**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	$V_{RWM}$				24	V
Reverse breakdown voltage	$V_{BR}$	$I_{BR}=1\text{mA}$	26.7			V
Reverse leakage current	$I_R$	$V_R=24\text{V}$ Each I/O pin			1	$\mu\text{A}$
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=1\text{A}$			40	V
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=3\text{A}$			50	V
Peak pulse current ( $t_p=8/20\mu\text{s}$ )	$I_{PP}$				3	A
Off state junction capacitance	$C_J$	0Vdc, $f=1\text{MHz}$ Between I/O pins and GND		12		pF

**Typical Characteristics Curves**

Figure 1. Power Derating Curve

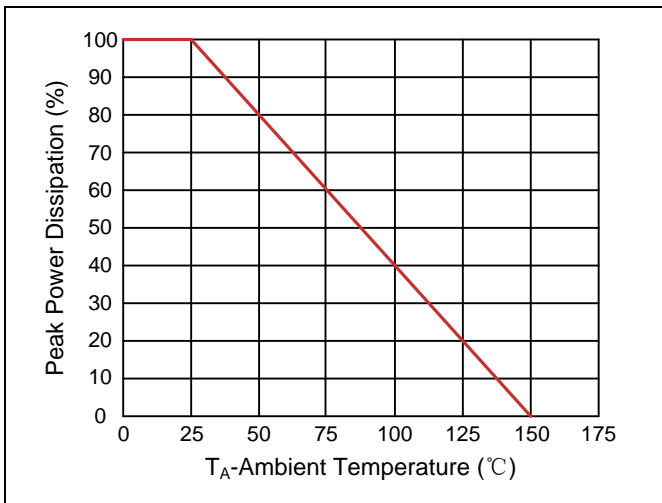


Figure 2. Pulse Waveforms

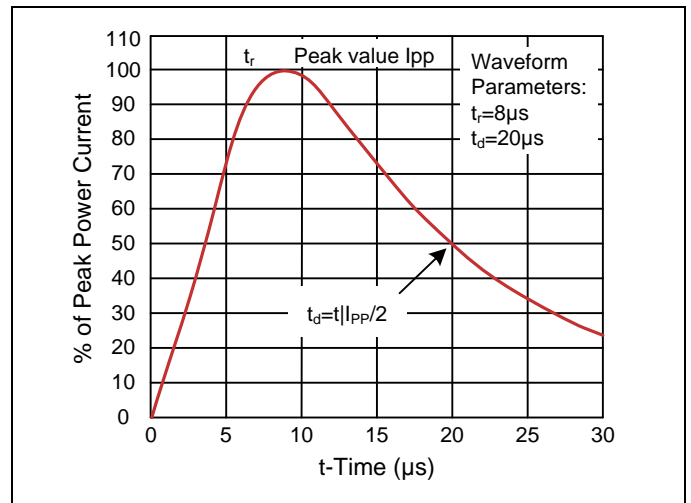


Figure 3. Clamping Voltage vs. Peak Pulse Current

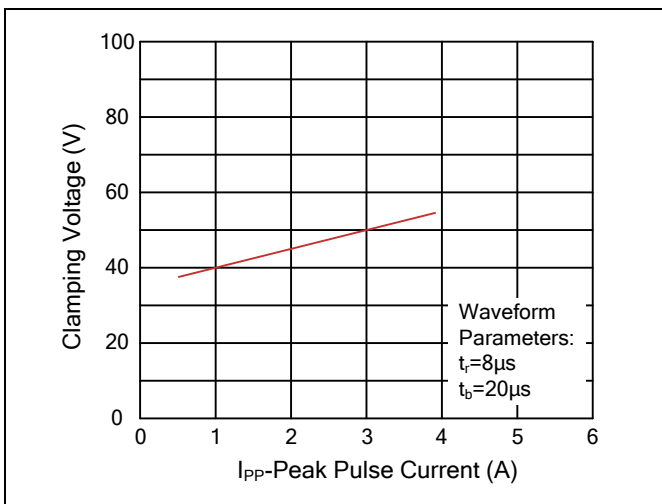
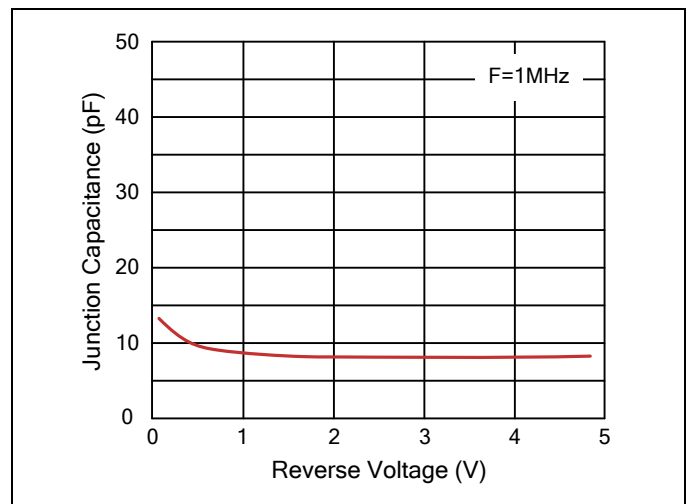
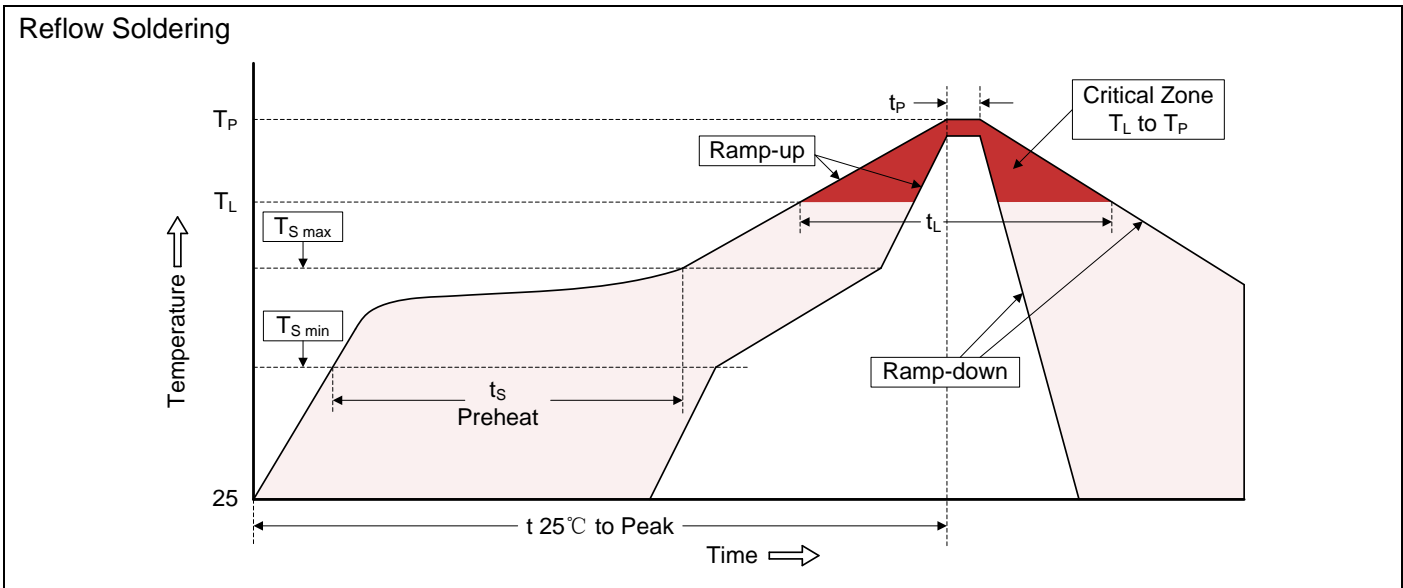


Figure 4. Normalized Capacitance vs. Reverse Voltage



**Recommended Soldering Conditions**

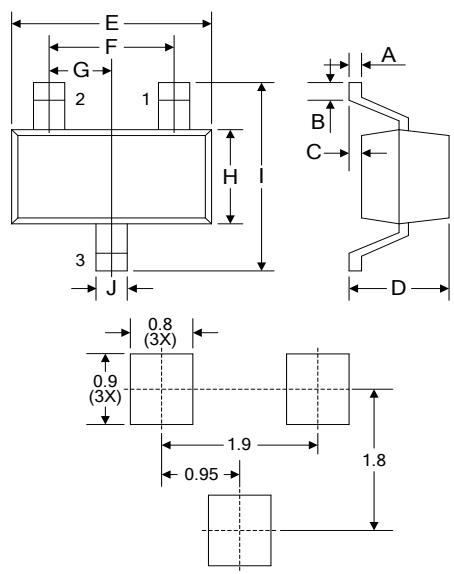


**Recommended Conditions**

Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat -Temperature Min ( $T_{S\ min}$ ) -Temperature Max ( $T_{S\ max}$ ) -Time (min to max) ( $t_s$ )	150°C 200°C 60-180 seconds
$T_{S\ max}$ to $T_L$ -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature ( $T_L$ ) -Time ( $t_L$ )	217°C 60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_p$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

**Dimensions (SOT-23)**

Symbol	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.08	0.18	0.003	0.007
B	0.15	-	0.006	-
C	-	0.13	-	0.005
D	0.89	1.09	0.035	0.043
E	2.80	3.05	0.110	0.120
F	1.90		0.075	
G	0.95		0.037	
H	1.19	1.40	0.047	0.055
I	2.10	2.49	0.083	0.098
J	0.35	0.50	0.014	0.020



**Packaging**

Tape		Symbol	Dimension (mm)
		W	8.00±0.30
		P0	4.00±0.10
		P1	4.00±0.10
		P2	2.00±0.10
		D0	Φ1.55±0.10
		D1	Φ1.00±0.05
		E	1.75±0.10
		F	3.50±0.10
		A	3.10±0.10
		A0	2.10±0.10
		B	2.75±0.10
		B0	0.65±0.10
		K	1.10±0.10
		t	0.20±0.05
Reel		D	Φ178.0±2.0
		D2	Φ13.0
		W1	9.5
		Quantity: 3000PCS	